

PCN Number:	20190923000.1		PCN Date:	Oct 23 2019										
Title:	Qualification of Hana as an alternate Assembly site for Select Devices in the DQN Package													
Customer Contact:	PCN Manager	Dept:	Quality Services											
Proposed 1st Ship Date:	Jan 23 2020	Estimated Sample Availability:	Date provided at sample request											
Change Type:														
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site									
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material									
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process									
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site									
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials									
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process									
PCN Details														
Description of Change:														
Texas Instruments is pleased to announce the qualification of Hana as an Additional Assembly site for the list of devices shown below. Current assembly site and Material differences are as follows:														
<table border="1"> <thead> <tr> <th></th> <th>JCET</th> <th>Hana</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>S#120402001600</td> <td>SID#400194</td> </tr> <tr> <td>Mold Compound</td> <td>S#120903003009</td> <td>SID#450176</td> </tr> </tbody> </table>							JCET	Hana	Mount Compound	S#120402001600	SID#400194	Mold Compound	S#120903003009	SID#450176
	JCET	Hana												
Mount Compound	S#120402001600	SID#400194												
Mold Compound	S#120903003009	SID#450176												
Reason for Change:														
Continuity of Supply														
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):														
None														
Anticipated impact on Material Declaration														
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp											
Changes to product identification resulting from this PCN:														
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City											
JCET	JCE	CHN	Jiangyin											
HANA	HNT	THA	Ayutthaya											
Sample product shipping label (not actual product label)														



MADE IN: Malaysia
2DC: 20:

MSL '2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:

ITEM:

LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TLV75507PDQNR	TLV75512PDQNR	TLV75519PDQNR	TLV75528PDQNT
TLV75507PDQNT	TLV75512PDQNT	TLV75519PDQNT	TLV75530PDQNR
TLV75509PDQNR	TLV75515PDQNR	TLV75525PDQNR	TLV75530PDQNT
TLV75509PDQNT	TLV75515PDQNT	TLV75525PDQNT	TLV75533PDQNR
TLV75510PDQNR	TLV75518PDQNR	TLV75528PDQNR	TLV75533PDQNT
TLV75510PDQNT	TLV75518PDQNT		



**TI Information
Selective Disclosure**

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV75550PDQNR	QBS Product Reference: TLV75506PDQNR	QBS Product Reference: TLV75550PDQNR	QBS Product Reference: TLV75730PDRV	QBS Product Reference: TLV75733PDRV	QBS Process Reference: TLV62568DRV	QBS Package Reference: TLV70750PDQD
AC	Autoclave 121C	96 Hours	-	-	-	-	-	3/231/0	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	-	Pass	Pass	-
EDR	EEPROM Data Retention, 170C	420 Hours	-	-	-	-	3/231/0	-	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	-	-	3/3000/0	-
HAST	Biased HAST, 110C/85%RH	264 Hours	1/77/0	-	1/77/0	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0	3/231/0
HBM	ESD - HBM	3000 V	-	-	-	-	1/3/0	-	-
CDM	ESD - CDM	1500V	1/3/0	-	1/3/0	-	-	2/6/0	-
HTOL	Life Test, 150C	300 Hours	-	-	1/77/0	2/154/0	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	1/77/0	-	3/231/0	3/231/0	3/231/0
LU	Latch-up.	(per JESD78)	-	-	-	-	1/6/0	2/12/0	1/6/0
SD	Solderability	8 Hours Steam Age	-	-	-	-	-	-	2/44/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	1/77/0	-	3/231/0	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Hours	-	-	-	-	-	-	3/231/0
UHAST	Unbiased HAST, 110C/85%RH	264 Hours	1/77/0	-	-	-	-	-	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	1/77/0	-	-	-	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	3/231/0
YLD	FTY and Bin Summary	Acceptable Yield	Pass	-	-	-	-	-	-

- QBS: Qual By Similarity

- Qual Devices qualified at LEVEL 1-260C: TLV75550PDQNR, TLV75533PDQNR, TLV75506PDQNR, TLV75510PDQNR, TLV75515PDQNR, TLV75525PDQNR, TLV75530PDQNR, TLV75518PDQNR, TLV75528PDQNR, TLV75512PDQNR

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent

HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

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